

#### **Applications**

- Low phase noise oscillators up to 16 GHz
- VCO's, DRO's and YIG oscillators
- Point-to-point radios
- Satellite communications
- Fiber optics, OC-192 and OC-768
- Local Multipoint Distribution Systems, LMDS

#### **Features**

- Low 1/f noise: -142 dBc/Hz at 100 Hz offset
- Phase noise: -167 dBc/Hz at 100 kHz offset
- Output power up to +13 dBm
- Operation down to 1 volt, 2 mA
- Gold bump pads for wire bond or flip chip (for direct die attachment)

#### **Ordering Information**

Туре	Package	Remark	
LPT16ED	Bare Die	Shipped in Waffle Pack	

#### **Product Description**

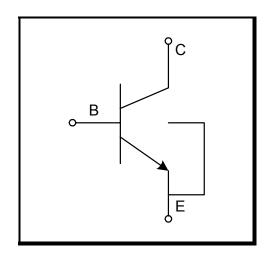
The LPT16ED is a silicon germanium low phase noise, high frequency NPN transistor for oscillator applications up to 16GHz.

The transistor exhibits low 1/f noise and provides +13 dBm typical output power at  $V_{\text{CE}}$  of 3V and  $I_{\text{C}}$  equal to 20 mA. It is easily operated from a single supply voltage with appropriate external passive components.

The silicon germanium technology used in this device provides outstanding high-frequency performance combined with high thermal conductivity and superior reliability under harsh operating and storage conditions.

A complete mechanical description of the transistor is available under SiGe Semiconductor Document 07MS001.

## **Functional Block Diagram**





### **Absolute Maximum Ratings**

Operation in excess of any one of Absolute Maximum Ratings may result in permanent damage. This is a high performance RF device with ESD rating < 2keV. Handling and assembly of this device should be done at ESD protected workstations.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CBO</sub>	Collector to Base Voltage		+13.0	V
$V_{CEO}$	Collector to Emitter Voltage		+4.0	V
$V_{EBO}$	Emitter to Base Voltage		+1.5	V
Ic	Collector Current		80	mA
I <sub>B</sub>	Base Current		2.0	mA
PT	Total Power Dissipation		250	mW
Tj	Junction Temperature		+150	°C
T <sub>STG</sub>	Storage Temperature	-65	+150	°C

#### **DC Electrical Characteristics**

Conditions: T<sub>A</sub> = unless otherwise specified 25°C

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
V <sub>BE</sub>	Base-emitter voltage	I <sub>C</sub> = 1μA	670	687	700	mV
BV <sub>CEO</sub>	Collector-emitter breakdown voltage	Open base	4.0	4.5	5.0	V
BV <sub>CES</sub>	Collector-emitter breakdown voltage	Base-emitter shorted via 100kΩ	14	15.0	16	V
BV <sub>EBO</sub>	Emitter-base breakdown voltage	I <sub>E</sub> = 100μA, open collector	2.0	2.3	2.6	V
BV <sub>CBO</sub>	Collector-base breakdown voltage	Open emitter	14	15.0	16	V
VA	Early voltage	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 3V	100	200	300	V
I <sub>CBO</sub>	Collector-base cutoff current	$V_{CB} = 5V$ and $I_E = 0$			100	pA
I <sub>EBO</sub>	Emitter-base cutoff current	V <sub>EB</sub> = 1.5V and I <sub>C</sub> = 0	5	10	15	μΑ
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 2V, I <sub>C</sub> = 20mA	50	60	150	

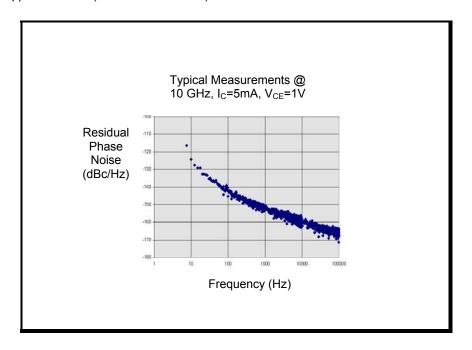


#### **AC Electrical Characteristics**

Symbol	Parameter	Note	Min.	Тур.	Max.	Unit
IS <sub>21</sub> I <sub>2</sub> Insertion Power Gain $(Z_S = Z_L = 50\Omega)$	V <sub>CE</sub> = 1.5V, I <sub>C</sub> = 10mA, f = 16GHz	0.7	1.0	1.3	dB	
	$(Z_{\rm S}=Z_{\rm L}=50\Omega)$	$V_{CE} = 3.0V, I_{C} = 20mA,$ f = 16GHz	2.3	2.6	2.9	dB
MAG/ MSG Maximum Available Gain or Maximum Stabl Gain		V <sub>CE</sub> = 1.5V, I <sub>C</sub> = 10mA, f = 16GHz	3.3	3.6	4.2	dB
		$V_{CE} = 3.0V, I_{C} = 20mA,$ f = 16GHz	4.9	5.2	5.6	dB

# **Typical Performance Characteristics**

Please refer to application note (Document 07AN001).

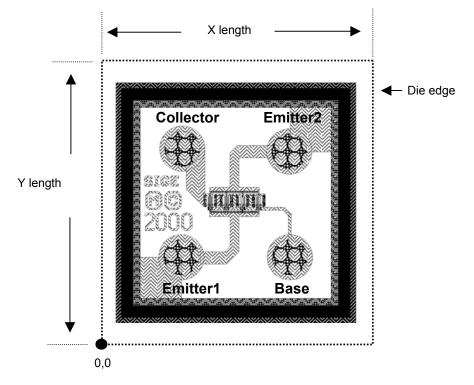


### **Typical Applications Information**

Series or parallel feedback oscillators at 5-16 GHz. (Please refer to application note, Document 07AN001).



# **Die and Pad Description**



Dimensions are relative to the 0,0 cut die corner.

Feature	Specification	Comments
Die thickness	10 mil +/- 1mil	
X length	15.3 mil +/- 1mil	
Y length	14.5 mil +/- 1mil	
Pad diameter	2.9 mil +/- 0.1mil	Pads are circular.
Pad pitch	6 mil +/- 0.1mil	Pad center to pad centre
Pad/bump height	1 mil +/- 0.05mil	
Pad/bump co-planarity	0.2 mil	

Pad Center	Position (X mil, Y mil) +/- 0.7mil relative to the 0,0 cut die corner		
Collector	5, 11		
Emitter1	5, 5		
Base	11, 5		
Emitter 2	11, 11		

Please refer to Document 01-MS-001 for SiGe's die inspection criteria.

For S-parameter data, please refer to SiGe Document 07SP001.



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#### Preliminary Information

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